

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT6332295

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
WEE AUN JASON LIM	10/01/2020
PAUL ARMAND ASENTISTA CALO	08/14/2020
TING SOON CHIN	08/21/2020
CHOOI MEI CHONG	08/14/2020
SANJAY KUMAR MURUGAN	08/14/2020
YING POK SAM	09/24/2020
CHEE VOON TAN	09/24/2020
RECEIVING PARTY DATA	
Name:	INFINEON TECHNOLOGIES AG
Street Address:	AM CAMPEON 1-15
City:	NEUBIBERG
State/Country:	GERMANY
Postal Code:	85579
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16991123
CORRESPONDENCE DATA	
Fax Number:	(919)948-3357
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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Correspondent Name:	MURPHY, BILAK & HOMILLER/INFINEON TECHNO
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Address Line 4:	CARY, NORTH CAROLINA 27518
ATTORNEY DOCKET NUMBER:	1012-2799 / 2019P51123 US
NAME OF SUBMITTER:	MARK R. BILAK
SIGNATURE:	/Mark R. Bilak, Reg. No. 47,423/
DATE SIGNED:	10/02/2020

PATENT

Total Attachments: 6

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**DECLARATION AND ASSIGNMENT
FOR PATENT AND DESIGN APPLICATIONS**

UNITED STATES PATENT RIGHTS, OR
UNITED STATES PLUS ALL FOREIGN PATENT RIGHTS

**Power Semiconductor Package and Method for Fabricating a Power Semiconductor
Package**

As a below named inventor (hereinafter designated as the undersigned), I hereby declare that:

This declaration is directed to the application attached hereto. If the application is not attached hereto, the application is as identified by the attorney docket number as set forth above and/or the following:

United States Application Number or PCT International Appln. No. 16/991,123

filed on Aug 12, 2020.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I have reviewed and understand the contents of the above-identified application, including the claims.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations § 1.56.

WHEREAS, the undersigned has invented certain at least one claim in the application identified.

WHEREAS, Infineon Technologies AG

of Am Campeon 1-15 Neubiberg 85579 Germany

its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefor in the United States of America and

in any foreign countries.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned has (have) sold, assigned and transferred, and by these considerations does (do) sell, assign and transfer unto said Assignee the full and exclusive right to the said invention in the United States of America, its territories, dependencies and possessions and the entire right, title and interest in and to any and all Letters Patent(s) which may be granted therefor in the United States of America, its territories, dependencies and possessions, and if the box above is designated, in any and all foreign countries; and to any and all divisions, reissues, continuations, conversions and extensions of all of the above for the full term or terms for which the same may be granted.

The undersigned agrees to execute all papers necessary in connection with this application and any continuing, divisional, conversion or reissue applications thereof or any other proceedings before the United States Patent and Trademark Office and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agrees to execute all papers and documents and to perform any act which may be necessary in connection with claims or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

The undersigned agrees to perform all affirmative acts which may be necessary to obtain a grant of (a) valid United States of America patent(s) and any foreign patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorizes and requests the Patent and Trademark Office Officials in the United States of America and in any foreign countries to issue any and all Letters Patent(s) resulting from said application or any continuing, divisional conversion or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has the full right to convey the entire interest herein assigned, and that he has not executed, and will not execute, any agreement in conflict herewith.


The undersigned hereby grants the Assignee's legal representatives the power to insert, before or after this document has been executed by the undersigned, any information to identify the instant patent application which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office.

The undersigned hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

The undersigned hereby acknowledges that any willful false statement made in this declaration is punishable under 18 U.S.C. § 1001 by fine or imprisonment of not more than five (5) years, or both.

In witness whereof, executed by the undersigned on the date opposite the undersigned name.

Full Name of Inventor:
24 September 2020
Date

Chee Voon Tan
DocuSigned by:

Inventor Signature
FB11C0E95F2349D...

Full Name of Inventor:
14 August 2020
Date

Chooi Mei Chong
DocuSigned by:

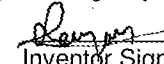
Inventor Signature

Full Name of Inventor:
14 August 2020
Date

Paul Armand Asentista Calo
DocuSigned by:

Inventor Signature
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Full Name of Inventor:
14 August 2020
Date

Sanjay Kumar Murugan
DocuSigned by:

Inventor Signature
5E8C673A0FD84D8...

Full Name of Inventor:
21 August 2020
Date

Ting Soon Chin
DocuSigned by:

Inventor Signature

Full Name of Inventor:

14 August 2020

Date

Wee Aun Jason Lim

DocuSigned by:

Jason Lim Wee Aun

Inventor Signature

Full Name of Inventor:

24 September 2020

Date

Ying Pok Sam

DocuSigned by:

YPSam

Inventor Signature

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in any foreign countries.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned has (have) sold, assigned and transferred, and by these considerations does (do) sell, assign and transfer unto said Assignee the full and exclusive right to the said invention in the United States of America, its territories, dependencies and possessions and the entire right, title and interest in and to any and all Letters Patent(s) which may be granted therefor in the United States of America, its territories, dependencies and possessions, and if the box above is designated, in any and all foreign countries; and to any and all divisions, reissues, continuations, conversions and extensions of all of the above for the full term or terms for which the same may be granted.

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In witness whereof, executed by the undersigned on the date opposite the undersigned name.

Full Name of Inventor:

Chee Voon Tan

Date

Inventor Signature

Full Name of Inventor:

Chooi Mei Chong

Date

Inventor Signature

Full Name of Inventor:

Paul Armand Asentista Calo

Date

Inventor Signature

Full Name of Inventor:

Sanjay Kumar Murugan

Date

Inventor Signature

Full Name of Inventor:

Ting Soon Chin

Date

Inventor Signature

Full Name of Inventor:

01 October 2020

Date

Wee Aun Jason Lim

DocuSigned by:

Jason Lim Wee Aun

Inventor Signature

Full Name of Inventor:

Ying Pok Sam

Date

Inventor Signature